



Material Content Data Sheet



Sales Product Name		BSZ0901NSI		Issued		27. September 2017		
MA#		MA001115484						
Package		PG-TSDSON-8-26		Weight*		36.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	1.71	1.71	17095	17095
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		267	
	non noble metal	iron	7439-89-6	0.197	0.53		5346	
wire	non noble metal	copper	7440-50-8	7.988	21.71	22.28	217073	222753
	noble metal	gold	7440-57-5	0.070	0.19	0.19	1895	1895
	organic material	carbon black	1333-86-4	0.037	0.10		1001	
encapsulation	plastics	epoxy resin	-	1.897	5.15		51544	
	inorganic material	silicondioxide	60676-86-0	16.482	44.80	50.05	447886	500431
leadfinish	non noble metal	tin	7440-31-5	0.395	1.07	1.07	10741	10741
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	552	552
solder	noble metal	silver	7440-22-4	0.023	0.06		636	
	non noble metal	tin	7440-31-5	0.019	0.05		509	
	non noble metal	lead	7439-92-1	0.895	2.43	2.54	24309	25454
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2554	
	non noble metal	copper	7440-50-8	3.816	10.37	10.64	103692	106406
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2752	
	non noble metal	copper	7440-50-8	4.112	11.17	11.46	111749	114673
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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